Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. - 20. (canceled)

- 21. (new) A process for the production of a printed substrate, which process comprises:
- (i) image-wise applying to a substrate a printing paste comprising:
 - (a) a matrix-forming condensate which comprises polyorganosiloxanes, obtainable by a sol-gel process, and
 - (b) at least one filler selected from coloring fillers, luminescent fillers, conductive fillers and catalytically active fillers; and
- (ii) densifying the image-wise applied paste to form a matrix which contains the at least one filler by a heat treatment at a temperature below the glass transition temperature of the thus-formed matrix.
- 22. (new) The process of claim 21, wherein the heat treatment is conducted at a temperature which is at least 200 °C below the glass transition temperature of the matrix.

- 23. (new) The process of claim 21, wherein the heat treatment is conducted at a temperature which is at least 400 °C below the glass transition temperature of the matrix.
- 24. (new) The process of claim 23, wherein the heat treatment is conducted at a temperature which is up to 700 °C below the glass transition temperature of the matrix.
- 25. (new) The process of claim 22, wherein the heat treatment is conducted at a temperature of form 400 °C to 800 °C.
- 26. (new) The process of claim 21, wherein the printing paste is applied to the substrate by a process which comprises one of screen printing and pad printing.
- 27. (new) The process of claim 21, wherein the substrate comprises at least one of a glass substrate, a glass-ceramic substrate and a ceramic substrate.
- 28. (new) The process of claim 27, wherein the substrate comprises a conductive coating.
- 29. (new) The process of claim 28, wherein the conductive coating comprises at least one of tin oxide and indium tin oxide.

- 30. (new) The process of claim 21, wherein the printed substrate comprises at least one of conductor tracks, spacers and a decorative pattern.
- 31. (new) The process of claim 30, wherein the printed substrate comprises conductor tracks.
- 32. (new) The process of claim 21, wherein the at least one filler comprises a conductive filler.
- 33. (new) The process of claim 21, wherein the at least one filler comprises a catalytically active filler.
- 34. (new) A composition comprising:
- (a) a matrix-forming condensate which comprises polyorganosiloxanes, obtainable by a sol-gel process which comprises a partial hydrolysis and polycondensation of:
 - (A) at least one organosilane of formula R_nSiX_(4-n), wherein each R independently represents a non-hydrolyzable group, each X independently represents a hydroxy group or a hydrolyzable group, and n represents 0, 1, 2 or 3; or an oligomer derived therefrom;

- (B) optionally, at least one silane of formula SiX_4 , wherein X is as defined above, and
- (C) optionally, one or more compounds of at least one of glass-forming elements and ceramic-forming elements;
- (b) at least one filler selected from coloring fillers, luminescent fillers, conductive fillers and catalytically active fillers;
- (c) at least one organic solvent having a boiling point of at least 150 °C; and
- (d) at least one rheology control agent.
- 35. (new) The composition of claim 34, wherein component (A) accounts for at least 40 mol%, based on the total of components (A) to (C).
- 36. (new) The composition of claim 34, wherein component (A) accounts for at least 60 mol%, based on the total of components (A) to (C).
- 37. (new) The composition of claim 35, wherein component (B) accounts for not more than 40 mol%, based on the total of components (A) to (C).
- 38. (new) The composition of claim 34, wherein the at least one filler comprises a

conductive filler.

- 39. (new) The composition of claim 38, wherein the conductive filler is present in an amount of from 50 to 80 % by weight.
- 40. (new) The composition of claim 39, wherein the conductive filler is present in an amount of from 70 to 75 % by weight.
- 41. (new) The composition of claim 34, wherein the at least one filler comprises a coloring filler.
- 42. (new) The composition of claim 34, wherein the at least one filler comprises a luminescent filler.
- 43. (new) The composition of claim 34, wherein the at least one filler comprises a catalytically active filler.
- 44. (new) The composition of claim 34, wherein the at least one filler comprises at least

one of a dye, a colored pigment, a photoluminescent substance, a electroluminescent substance, an electrically conductive material, a photoconductive material and a catalytically active material.

- 45. (new) The composition of claim 34, wherein the at least one filler comprises a particulate conductive material selected from gold, silver, copper, nickel, tungsten, molybdenum, tin oxide, indium tin oxide, lead zirconate titanate, graphite and combinations thereof.
- 46. (new) The composition of claim 34, wherein the composition is essentially free of glass particles.
- 47. (new) The composition of claim 34, wherein the at least one organic solvent comprises a solvent having a boiling point of at least 180 °C.
- 48. (new) The composition of claim 47, wherein the at least one organic solvent is present in an amount of up to 50 % by weight.
- 49. (new) The composition of claim 34, wherein the at least one rheology control agent

comprises an organic rheology control agent.

- 50. (new) The composition of claim 34, wherein the at least one rheology control agent comprises at least one of a fish oil, a cellulose, a cellulose derivative and a polyalcohol.
- 51. (new) The composition of claim 34, wherein the at least one rheology control agent is present in an amount of not more than 5 % by weight.
- 52. (new) The composition of claim 50, wherein the at least one rheology control agent is present in an amount of from 0.5 % by weight to 2 % by weight.
- 53. (new) A composition comprising:
- (a) a matrix-forming condensate which comprises polyorganosiloxanes, obtained by a solgel process which comprises a partial hydrolysis and polycondensation of:
 - (A) at least one organosilane of formula $R_nSiX_{(4-n)}$, wherein each R independently represents a non-hydrolyzable group, each X independently represents a hydroxy group or a hydrolyzable group, and n represents 0, 1, 2 or 3; or an oligomer derived therefrom;

- (B) optionally, at least one silane of formula SiX_4 , wherein X is as defined above, and
- (C) optionally, one or more compounds of at least one of glass-forming elements and ceramic-forming elements;

wherein component (A) accounts for at least 60 mol% of the total of components (A) to (C);

- (b) at least one filler which comprises a particulate conductive material selected from gold, silver, copper, nickel, tungsten, molybdenum, tin oxide, indium tin oxide, lead zirconate titanate, graphite and combinations thereof.;
- (c) 1 % by weight to 30 % by weight of at least one organic solvent having a boiling point of at least 200 °C; and
- (d) from 0.5 % by weight to 2 % by weight of a rheology control agent which comprises at least one of a fish oil, a cellulose, a cellulose derivative and a polyalcohol.